AOT2144L/AOB2144L

40V N-Channel MOSFET

General Description

- Trench Power MV MOSFET technology
- Low $R_{DS(ON)}$
- Low Gate Charge
- Opitimized Ruggedness
- RoHS and Halogen-Free Compliant

Applications

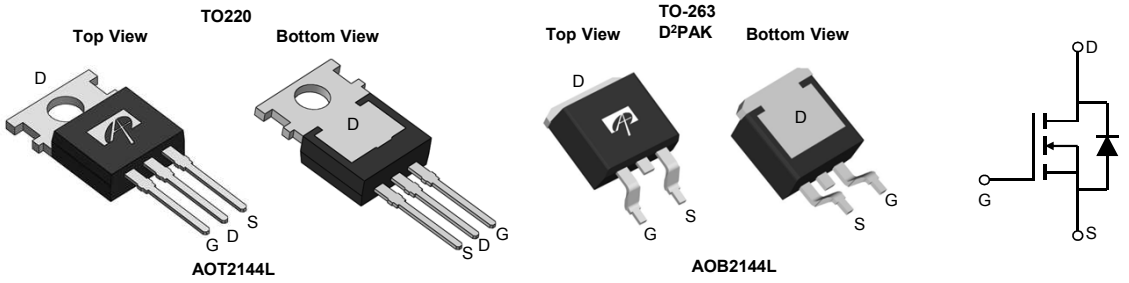
- DC Motor Driver
- Synchronous Rectification in DC/DC and AC/DC Converters

Product Summary

V_{DS}	40V
I_D (at V_{GS}=10V)	120 A
$R_{DS(ON)}$ (at V_{GS}=10V)	< 2.3mΩ
$R_{DS(ON)}$ (at V_{GS}=4.5V)	< 4mΩ

100% UIS Tested
100% Rg Tested

Green Product



Orderable Part Number	Package Type	Form	Minimum Order Quantity
AOT2144L	TO-220	Tube	1000
AOB2144L	TO-263	Tape & Reel	800

Absolute Maximum Ratings T_A=25°C unless otherwise noted

Parameter		Symbol	Maximum	Units
Drain-Source Voltage		V_{DS}	40	V
Gate-Source Voltage		V_{GS}	±20	V
Continuous Drain Current[G]	T_C=25°C	I_D	120 [G]	A
	T_C=25°C		205 [I]	
	T_C=100°C		120 [G]	
Pulsed Drain Current [C]		I_{DM}	772	
Continuous Drain Current	T_A=25°C	I_{DSM}	44	A
	T_A=70°C		35	
Avalanche Current [C]		I_{AS}	47	A
Avalanche energy	L=0.3mH [C]	E_{AS}	331	mJ
Power Dissipation [B]	T_C=25°C	P_D	187	W
	T_C=100°C		93	
Power Dissipation [A]	T_A=25°C	P_{DSM}	8.3	W
	T_A=70°C		5.3	
Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 175	°C

Thermal Characteristics

Parameter		Symbol	Typ	Max	Units
Maximum Junction-to-Ambient [A]	t ≤ 10s	$R_{\theta JA}$	12	15	°C/W
Maximum Junction-to-Ambient [A D]	Steady-State		50	60	°C/W
Maximum Junction-to-Case	Steady-State	$R_{\theta JC}$	0.6	0.8	°C/W

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	ID=250µA, VGS=0V	40			V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=40V, V_{GS}=0V			1	µA
		T_J=55°C			5	
I_{GSS}	Gate-Body leakage current	V_{DS}=0V, V_{GS}=±20V			±100	nA
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_D=250µA	1.4	1.9	2.4	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=10V, I_D=20A		1.85	2.3	mΩ
		T_J=125°C		2.5	3.1	
		V_{GS}=4.5V, I_D=20A		2.45	4	mΩ
g_{FS}	Forward Transconductance	V_{DS}=5V, I_D=20A		100		S
V_{SD}	Diode Forward Voltage	I_S=1A, V_{GS}=0V		0.7	1	V
I_S	Maximum Body-Diode Continuous Current [G]				120	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=20V, f=1MHz		5225		pF
C_{oss}	Output Capacitance			895		pF
C_{rss}	Reverse Transfer Capacitance			55		pF
R_g	Gate resistance	f=1MHz	1	2	3.1	Ω
SWITCHING PARAMETERS						
Q_g(10V)	Total Gate Charge	V_{GS}=10V, V_{DS}=20V, I_D=20A		68	95	nC
Q_g(4.5V)	Total Gate Charge			28	40	nC
Q_{gs}	Gate Source Charge			16.5		nC
Q_{gd}	Gate Drain Charge			4.5		nC
Q_{oss}	Output Charge	V_{GS}=0V, V_{DS}=20V		37		nC
$t_{D(on)}$	Turn-On DelayTime	V_{GS}=10V, V_{DS}=20V, R_L=1Ω, R_{GEN}=3Ω		12.5		ns
t_r	Turn-On Rise Time			9.5		ns
$t_{D(off)}$	Turn-Off DelayTime			57.5		ns
t_f	Turn-Off Fall Time			10.5		ns
t_{rr}	Body Diode Reverse Recovery Time	I_F=20A, di/dt=500A/µs		20		ns
Q_{rr}	Body Diode Reverse Recovery Charge	I_F=20A, di/dt=500A/µs		60		nC

A. The value of $R_{\theta JA}$ is measured with the device mounted on 1in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25° C. The Power dissipation P_{DSM} is based on $R_{\theta JA}$ t≤ 10s and the maximum allowed junction temperature of 150° C. The value in any given application depends on the user's specific board design, and the maximum temperature of 175° C may be used if the PCB allows it.
B. The power dissipation P_D is based on $T_{J(MAX)}$=175° C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.
C. Single pulse width limited by junction temperature $T_{J(MAX)}$=175° C.
D. The $R_{\theta JA}$ is the sum of the thermal impedance from junction to case $R_{\theta JC}$ and case to ambient.
E. The static characteristics in Figures 1 to 6 are obtained using <300µs pulses, duty cycle 0.5% max.
F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of $T_{J(MAX)}$=175° C. The SOA curve provides a single pulse rating.
G. The maximum current rating is package limited.
H. These tests are performed with the device mounted on 1 in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25° C.
I. The maximum current rating is silicon limited

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

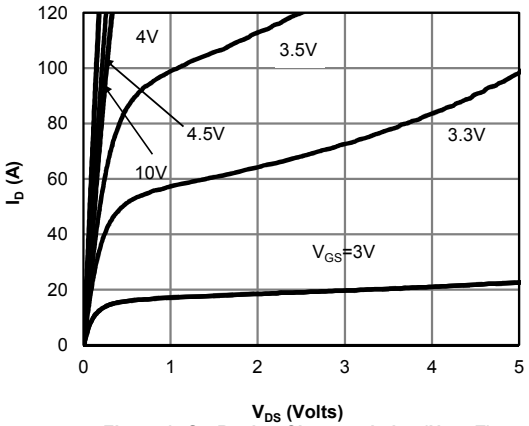


Figure 1: On-Region Characteristics (Note E)

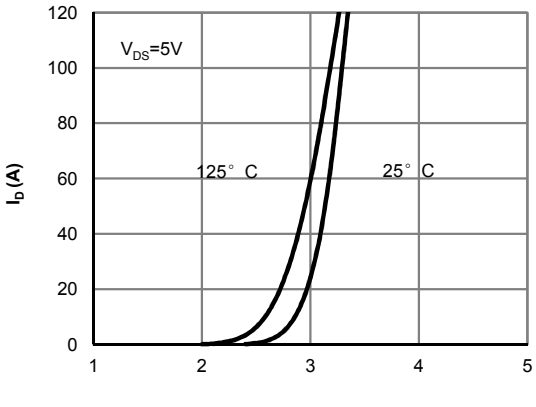


Figure 2: Transfer Characteristics (Note E)

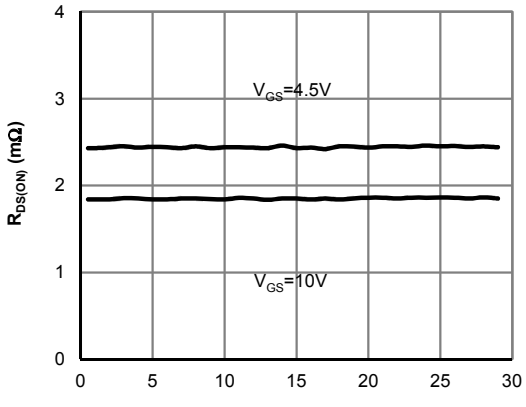


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

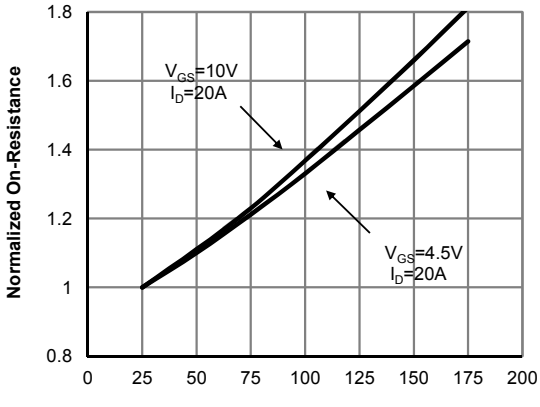


Figure 4: On-Resistance vs. Junction Temperature (Note E)

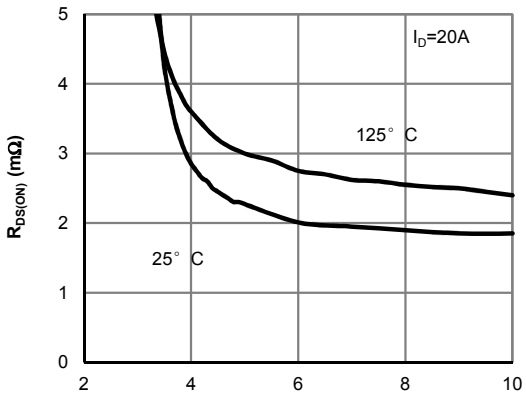


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

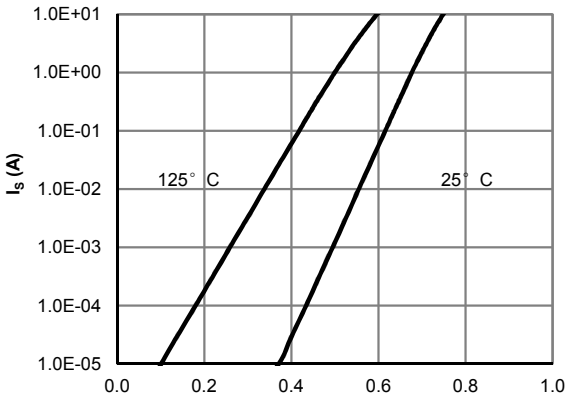


Figure 6: Body-Diode Characteristics (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

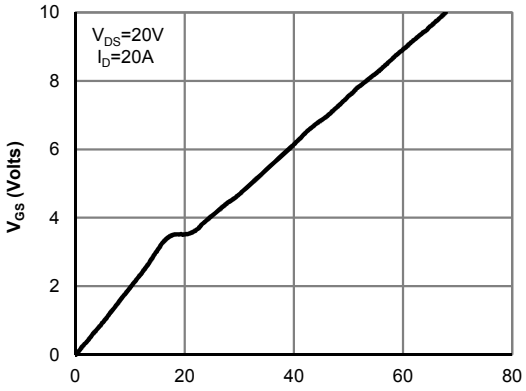


Figure 7: Gate-Charge Characteristics

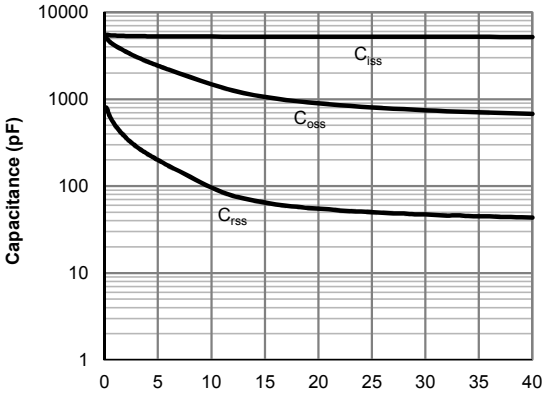
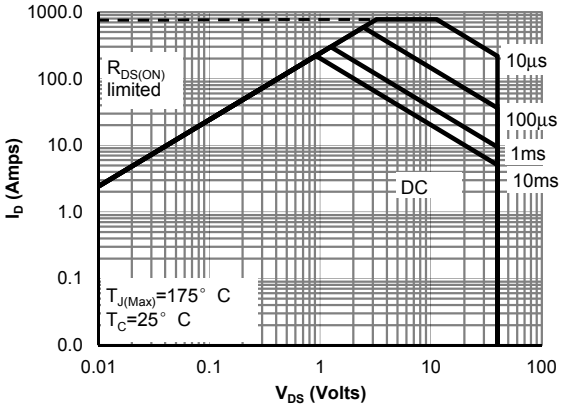


Figure 8: Capacitance Characteristics



V_{GS}> or equal to 4.5V

Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

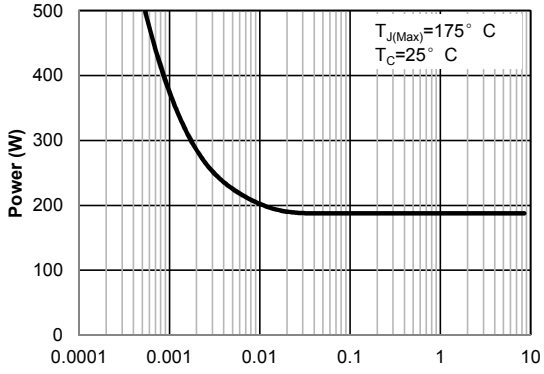


Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)

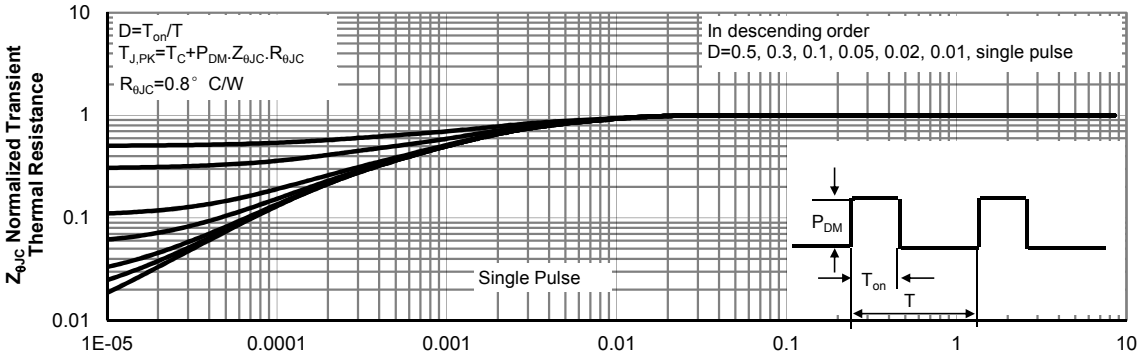


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

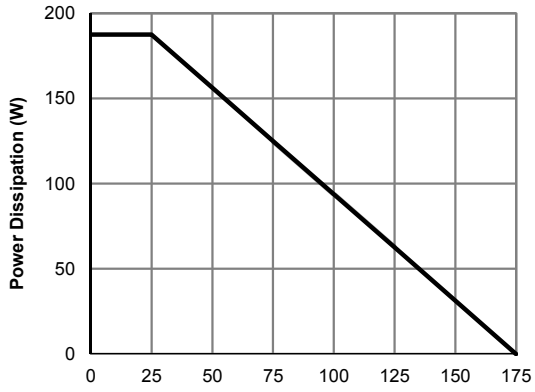


Figure 12: Power De-rating (Note F)

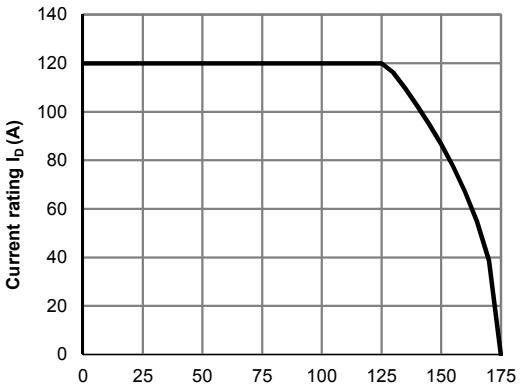


Figure 13: Current De-rating (Note F)

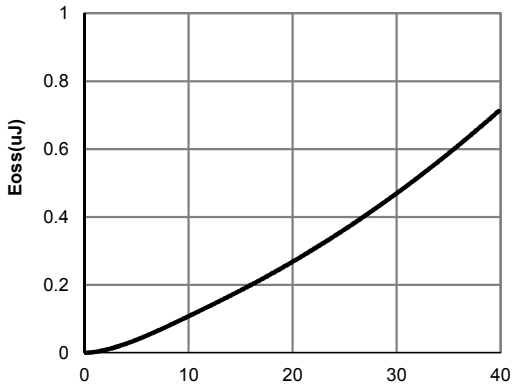


Figure 14: Coss stored Energy

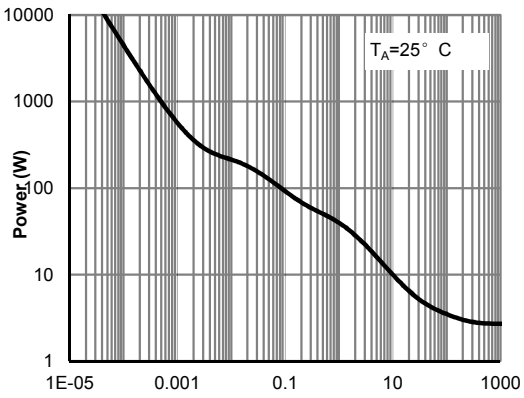


Figure 15: Single Pulse Power Rating Junction-to-Ambient (Note H)

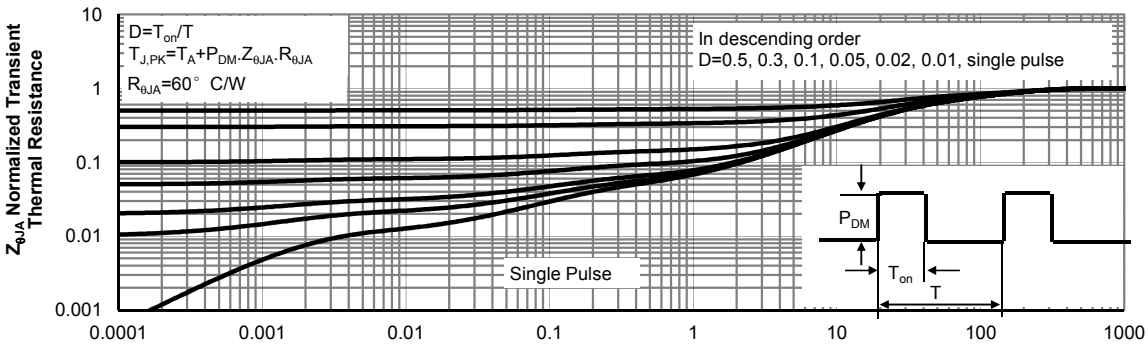


Figure 16: Normalized Maximum Transient Thermal Impedance (Note H)

Figure A: Gate Charge Test Circuit & Waveforms

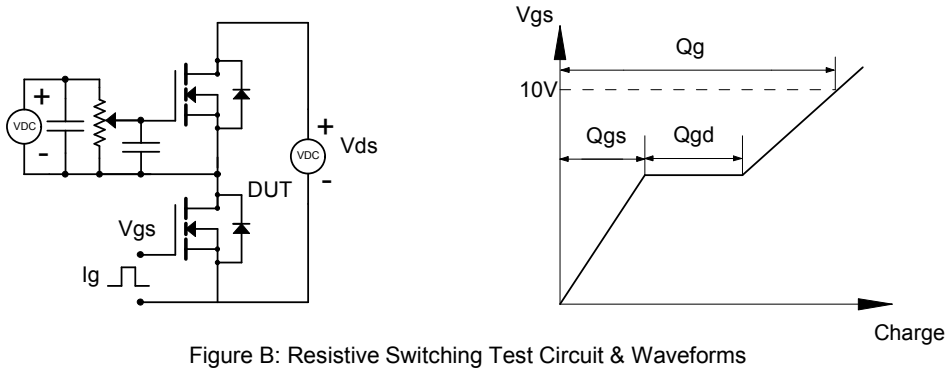


Figure B: Resistive Switching Test Circuit & Waveforms

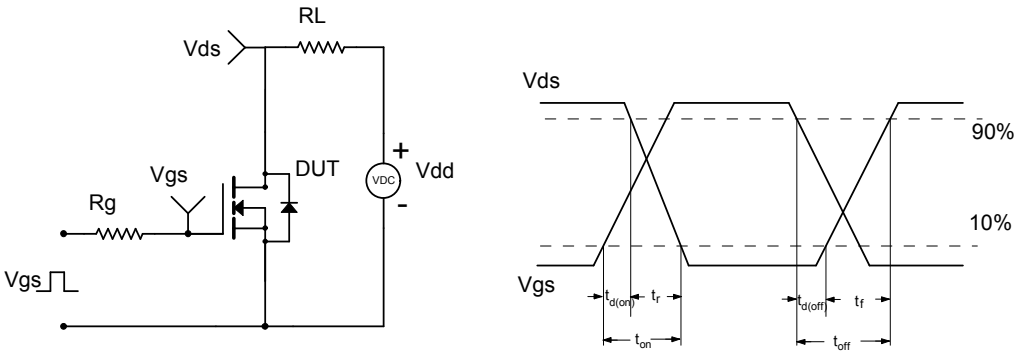


Figure C: Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

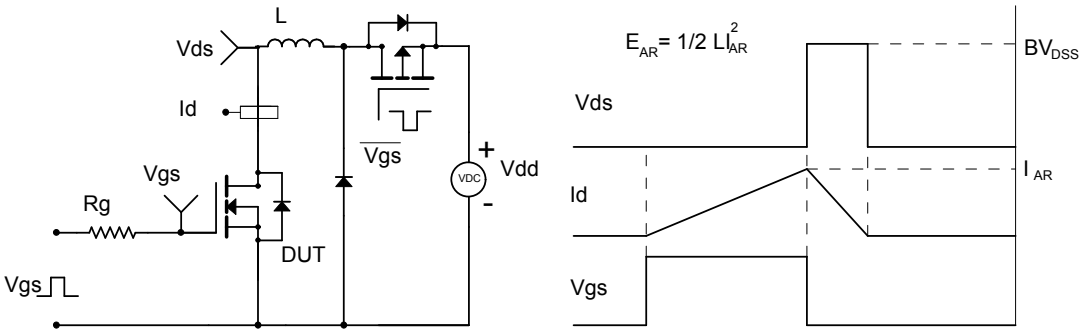


Figure D: Diode Recovery Test Circuit & Waveforms